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INFORMATION DISCLOSURE	Complete if Known		
	Application Number	10/612834	
STATEMENT BY APPLICANT US as many sheets as nocessary) MAY 2 4 2004 Sheet 140EMATH	Filing Date	June 30, 2003	
	First Named Inventor	Dani, Ashay	
	Group Art Unit	3743	
	Examiner Name	Unknown	
	Attorney Docket No: 8	884.945US1	

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